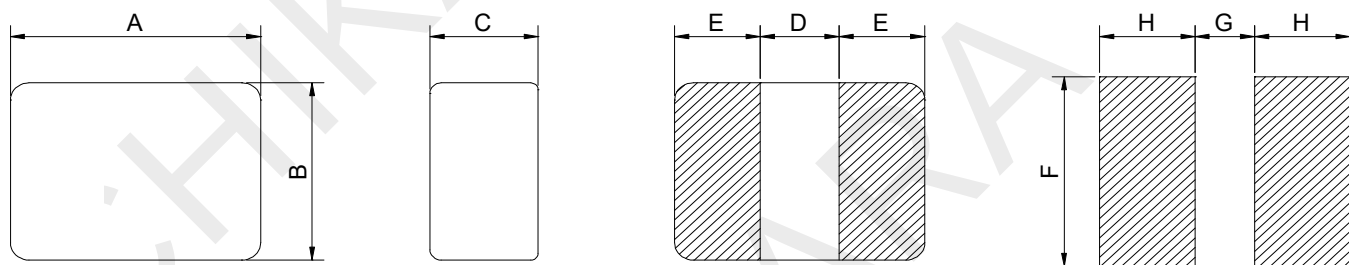


Features

- Compact design, Flat wire
- Storage temperature range:-55°C to + 125°C
- Operating temperature range:-55°C to + 125°C
(including coil's self-temperature rise)
- Moisture sensitivity level:1
- Packaging:3000pcs. Per 7-inch reel
- RoHs&Halogen-free compliant



Mechanical Dimension(Unit:mm)



Recommended Layout

A	B	C	D	E	F	G	H
2.5±0.2	2.0±0.2	1.05Max.	0.8±0.2	0.85±0.2	2.2	0.7	1.0

Part Number Description

SP16 - 252010 R22 M
① ② ③ ④

①	Type
②	Dimensions
③	Inductance value
④	Tolerance code

Electrical Schematic

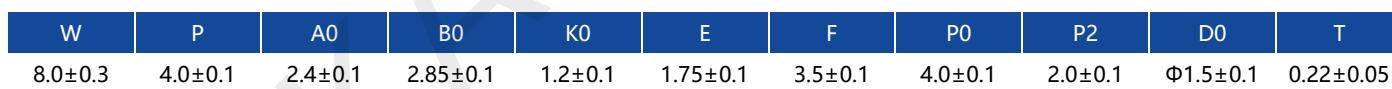


Electrical Characteristic

Part Number	Inductance L0(μH)	DCR		Isat		Irms	
		(mΩ)Max.	(mΩ)Typ.	(A)Max.	(A)Typ.	(A)Max.	(A)Typ.
SP16-252010R22M	0.22±20%	17.0	12.0	7.9	8.6	6.5	6.8
SP16-252010R24M	0.24±20%	17.0	12.0	7.8	8.5	6.4	6.7
SP16-252010R33M	0.33±20%	19.0	13.0	7.2	7.6	6.2	6.5
SP16-252010R47M	0.47±20%	22.0	15.0	6.5	7.2	5.6	6.1
SP16-252010R68M	0.68±20%	27.0	23.0	5.5	5.9	5.0	5.6
SP16-252010R82M	0.82±20%	29.0	24.0	4.8	5.3	4.1	4.5
SP16-2520101R0M	1.0±20%	30.0	25.0	4.8	5.4	4.1	4.7
SP16-2520101R5M	1.5±20%	55.0	45.0	3.9	4.3	3.0	3.4
SP16-2520102R2M	2.2±20%	70.0	62.0	3.0	3.3	2.1	2.4
SP16-2520103R3M	3.3±20%	100	86.0	2.5	2.8	2.1	2.5
SP16-2520104R7M	4.7±20%	180	160	2.0	2.6	1.6	2.0
SP16-2520106R8M	6.8±20%	320	270	1.9	2.4	1.4	1.6
SP16-252010100M	10±20%	560	500	1.4	1.6	0.9	1.1

- Test frequency and voltage:1MHz,1Vrms.
- All test data referenced to 25°C ambient.
- Absolute maximum voltage: 20Vdc.
- Saturation current(Isat) will cause L0 to drop approximately 30%.
- Heat rated current(Irms) will cause the coil temperature rise approximately Δt of 40°C.
- Heat rated current (Irms) is tested on a typical PCB and apply a constant current in still air. The temperature rise is dependent on the application system condition including PCB PAD pattern, trace width and thickness and adjacent components etc. It' s suggested to verify the temperature rise of the component under the real operation application conditions.

- Carrier Tape (Unit:mm)

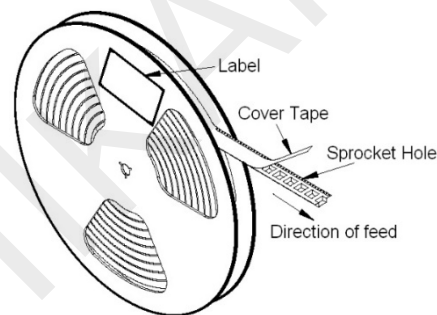


- Reel (Unit:mm)

A	B	C	D
$\Phi 178 \pm 2.0$	11.5Max.	$\Phi 50 \text{Min.}$	9.0 ± 0.5



Peel-off strength	Peel-off angle	Peel-off speed
F=0.1N~1.0N	165°~180°	300mm/min.



※ Packing is referred to the international standard IEC 60286-3.

- Package Quantity

Parts per reel
3000Pcs

Soldering Specification

- Reflow profile for SMT components



- Classification of peak package body temperature (T_P)

	Package Thickness	Package Volume		
		<350mm ³	350~2000mm ³	>2000mm ³
PB-Free Assembly	<1.6mm	260°C	260°C	260°C
	1.6~2.5mm	260°C	250°C	245°C
	≥2.5mm	250°C	245°C	245°C

※ Reflow is referred to standard IPC/JEDEC J-STD-020D.